

SN54AC563, SN74AC563 OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS

SCAS552C – NOVEMBER 1995 – REVISED OCTOBER 2003

- 2-V to 6-V V_{CC} Operation
- Inputs Accept Voltages to 6 V
- Max t_{pd} of 9 ns at 5 V
- 3-State Inverting Outputs Drive Bus Lines Directly
- Full Parallel Access for Loading
- Flow-Through Architecture to Optimize PCB Layout

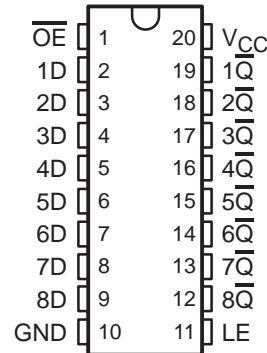
description/ordering information

The 'AC563 devices are octal D-type transparent latches with 3-state outputs. When the latch-enable (LE) input is high, the \bar{Q} outputs follow the complements of the data (D) inputs. When LE is taken low, the \bar{Q} outputs are latched at the inverse logic levels set up at the D inputs.

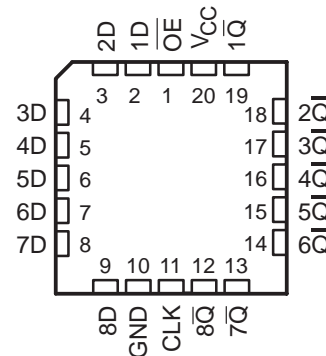
A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

\overline{OE} does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

SN54AC563 . . . J OR W PACKAGE
SN74AC563 . . . DB, DW, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AC563 . . . FK PACKAGE
(TOP VIEW)



ORDERING INFORMATION

| T_A | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------|---------------|-----------------------|------------------|
| -40°C to 85°C | PDIP – N | Tube | SN74AC563N | SN74AC563N |
| | SOIC – DW | Tube | SN74AC563DW | AC563 |
| | | Tape and reel | SN74AC563DWR | |
| | SOP – NS | Tape and reel | SN74AC563NSR | AC563 |
| | SSOP – DB | Tape and reel | SN74AC563DBR | AC563 |
| | TSSOP – PW | Tube | SN74AC563PW | AC563 |
| Tape and reel | | SN74AC563PWR | | |
| -55°C to 125°C | CDIP – J | Tube | SNJ54AC563J | SNJ54AC563J |
| | CFP – W | Tube | SNJ54AC563W | SNJ54AC563W |
| | LCCC – FK | Tube | SNJ54AC563FK | SNJ54AC563FK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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 **TEXAS
INSTRUMENTS**

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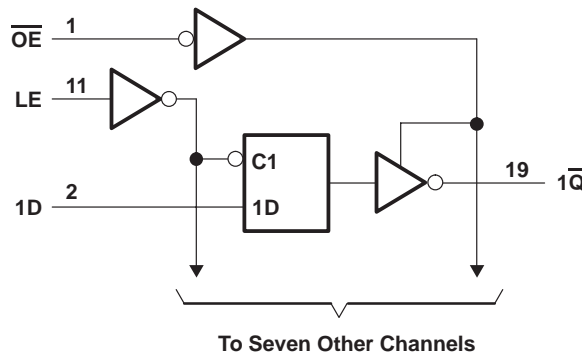
description/ordering information (continued)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE
(each latch)

| INPUTS | | | OUTPUT |
|-----------------|----|---|------------------|
| \overline{OE} | LE | D | \overline{Q} |
| L | H | H | L |
| L | H | L | H |
| L | L | X | \overline{Q}_0 |
| H | X | X | Z |

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|--|----------------------------|
| Supply voltage range, V_{CC} | -0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | -0.5 V to $V_{CC} + 0.5$ V |
| Output voltage range, V_O (see Note 1) | -0.5 V to $V_{CC} + 0.5$ V |
| Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) | ± 20 mA |
| Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) | ± 20 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ± 50 mA |
| Continuous current through V_{CC} or GND | ± 200 mA |
| Package thermal impedance, θ_{JA} (see Note 2): | |
| DB package | 70°C/W |
| DW package | 58°C/W |
| N package | 69°C/W |
| NS package | 60°C/W |
| PW package | 83°C/W |
| Storage temperature range, T_{stg} | -65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

SN54AC563, SN74AC563 OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 3)

| | | SN54AC563 | | SN74AC563 | | UNIT |
|---------------------|------------------------------------|-------------------------|----------|-----------|----------|------|
| | | MIN | MAX | MIN | MAX | |
| V_{CC} | Supply voltage | 2 | 6 | 2 | 6 | V |
| V_{IH} | High-level input voltage | $V_{CC} = 3\text{ V}$ | | 2.1 | | V |
| | | $V_{CC} = 4.5\text{ V}$ | | 3.15 | | |
| | | $V_{CC} = 5.5\text{ V}$ | | 3.85 | | |
| V_{IL} | Low-level input voltage | $V_{CC} = 3\text{ V}$ | | 0.9 | | V |
| | | $V_{CC} = 4.5\text{ V}$ | | 1.35 | | |
| | | $V_{CC} = 5.5\text{ V}$ | | 1.65 | | |
| V_I | Input voltage | 0 | V_{CC} | 0 | V_{CC} | V |
| V_O | Output voltage | 0 | V_{CC} | 0 | V_{CC} | V |
| I_{OH} | High-level output current | $V_{CC} = 3\text{ V}$ | | -12 | | mA |
| | | $V_{CC} = 4.5\text{ V}$ | | -24 | | |
| | | $V_{CC} = 5.5\text{ V}$ | | -24 | | |
| I_{OL} | Low-level output current | $V_{CC} = 3\text{ V}$ | | 12 | | mA |
| | | $V_{CC} = 4.5\text{ V}$ | | 24 | | |
| | | $V_{CC} = 5.5\text{ V}$ | | 24 | | |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | 8 | | 8 | | ns/V |
| T_A | Operating free-air temperature | -55 | 125 | -40 | 85 | °C |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V_{CC} | $T_A = 25^\circ\text{C}$ | | | SN54AC563 | | SN74AC563 | | UNIT |
|-----------------------------------|----------------------------------|----------|--------------------------|-------|-----------|-----------|---------|-----------|---------------|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| V_{OH} | $I_{OH} = -50\ \mu\text{A}$ | 3 V | 2.99 | | | 2.9 | | 2.9 | V | |
| | | 4.5 V | 4.49 | | | 4.4 | | 4.4 | | |
| | | 5.5 V | 5.49 | | | 5.4 | | 5.4 | | |
| | $I_{OH} = -12\ \text{mA}$ | 3 V | 2.56 | | | 2.48 | | 2.46 | | |
| | | 4.5 V | 3.86 | | | 3.8 | | 3.76 | | |
| | | 5.5 V | 4.86 | | | 4.8 | | 4.76 | | |
| $I_{OH} = -75\ \text{mA}^\dagger$ | 5.5 V | | | | 3.85 | | 3.85 | | | |
| V_{OL} | $I_{OL} = 50\ \mu\text{A}$ | 3 V | | 0.002 | 0.1 | | 0.1 | 0.1 | V | |
| | | 4.5 V | | 0.001 | 0.1 | | 0.1 | 0.1 | | |
| | | 5.5 V | | 0.001 | 0.1 | | 0.1 | 0.1 | | |
| | $I_{OL} = 12\ \text{mA}$ | 3 V | | | 0.36 | | 0.5 | 0.44 | | |
| | | 4.5 V | | | 0.36 | | 0.5 | 0.44 | | |
| | | 5.5 V | | | 0.36 | | 0.5 | 0.44 | | |
| $I_{OL} = 75\ \text{mA}^\dagger$ | 5.5 V | | | | 1.65 | | 1.65 | | | |
| I_I | $V_I = V_{CC}$ or GND | 5.5 V | | | ± 0.1 | | ± 1 | ± 1 | μA | |
| I_{OZ} | $V_O = V_{CC}$ or GND | 5.5 V | | | ± 0.5 | | ± 5 | ± 5 | μA | |
| I_{CC} | $V_I = V_{CC}$ or GND, $I_O = 0$ | 5.5 V | | | 8 | | | 80 | μA | |
| C_i | $V_I = V_{CC}$ or GND | 5 V | | 4.5 | | | | | pF | |

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

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timing requirements over recommended operating free-air temperature range, $V_{CC} = 3.3 V \pm 0.3 V$ (unless otherwise noted) (see Figure 1)

| | | $T_A = 25^\circ C$ | | SN54AC563 | | SN74AC563 | | UNIT |
|----------|---|--------------------|-----|-----------|-----|-----------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_w | Pulse duration, LE high | 6 | | 8 | | 7 | | ns |
| t_{su} | Setup time, data before LE \downarrow | 2.5 | | 5 | | 3 | | ns |
| t_h | Hold time, data after LE \downarrow | 2 | | 3 | | 2 | | ns |

timing requirements over recommended operating free-air temperature range, $V_{CC} = 5 V \pm 0.5 V$ (unless otherwise noted) (see Figure 1)

| | | $T_A = 25^\circ C$ | | SN54AC563 | | SN74AC563 | | UNIT |
|----------|---|--------------------|-----|-----------|-----|-----------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_w | Pulse duration, LE high | 4 | | 6 | | 5 | | ns |
| t_{su} | Setup time, data before LE \downarrow | 2 | | 4.5 | | 2.5 | | ns |
| t_h | Hold time, data after LE \downarrow | 2 | | 3 | | 2 | | ns |

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 3.3 V \pm 0.3 V$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $T_A = 25^\circ C$ | | | SN54AC563 | | SN74AC563 | | UNIT |
|-----------|-----------------|-------------|--------------------|-----|------|-----------|------|-----------|------|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t_{PLH} | D | \bar{Q} | 3.5 | 5.3 | 13 | 1.5 | 16.5 | 3.5 | 15 | ns |
| t_{PHL} | | | 3.5 | 5.6 | 12 | 1.5 | 15.5 | 3.5 | 14 | |
| t_{PLH} | LE | \bar{Q} | 3.5 | 4.6 | 13 | 1.5 | 16.5 | 3.5 | 15 | ns |
| t_{PHL} | | | 3.5 | 4.8 | 12 | 1.5 | 15.5 | 3.5 | 14 | |
| t_{PZH} | \overline{OE} | \bar{Q} | 2.5 | 5.3 | 11 | 1.5 | 13.5 | 2.5 | 12 | ns |
| t_{PZL} | | | 3 | 5.4 | 11 | 1.5 | 14 | 3.5 | 12.5 | |
| t_{PHZ} | \overline{OE} | \bar{Q} | 4 | 6 | 12.5 | 1.5 | 15 | 4.5 | 13.5 | ns |
| t_{PLZ} | | | 2 | 5.1 | 9.5 | 1.5 | 12 | 2.5 | 10.5 | |

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5 V \pm 0.5 V$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $T_A = 25^\circ C$ | | | SN54AC563 | | SN74AC563 | | UNIT |
|-----------|-----------------|-------------|--------------------|-----|-----|-----------|------|-----------|------|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t_{PLH} | D | \bar{Q} | 2 | 5.3 | 10 | 1.5 | 13 | 2 | 11.5 | ns |
| t_{PHL} | | | 2 | 5.6 | 9.5 | 1.5 | 12.5 | 2 | 11 | |
| t_{PLH} | LE | \bar{Q} | 2 | 4.6 | 9.5 | 1.5 | 12.5 | 2 | 11 | ns |
| t_{PHL} | | | 2 | 4.8 | 8.5 | 1.5 | 11.5 | 2 | 9.5 | |
| t_{PZH} | \overline{OE} | \bar{Q} | 2 | 5.3 | 9 | 1.5 | 11.5 | 2 | 10 | ns |
| t_{PZL} | | | 1.5 | 5.4 | 8.5 | 1.5 | 11 | 2 | 9.5 | |
| t_{PHZ} | \overline{OE} | \bar{Q} | 2 | 6 | 11 | 1.5 | 13.5 | 2 | 12 | ns |
| t_{PLZ} | | | 1.5 | 5.1 | 8 | 1.5 | 10.5 | 1.5 | 9 | |

operating characteristics, $V_{CC} = 5 V, T_A = 25^\circ C$

| PARAMETER | TEST CONDITIONS | TYP | UNIT |
|--|--------------------------|-----|------|
| C_{pd} Power dissipation capacitance | $C_L = 50 pF, f = 1 MHz$ | 25 | pF |

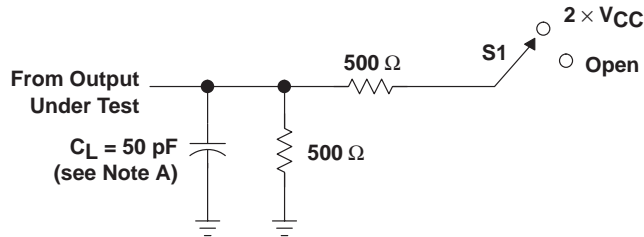
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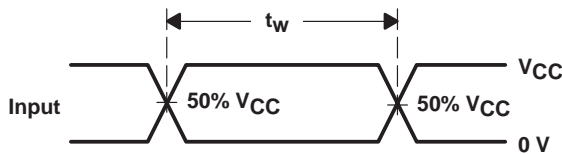
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PARAMETER MEASUREMENT INFORMATION

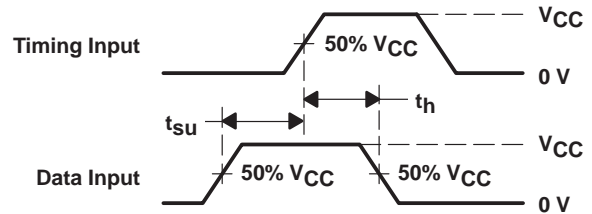


LOAD CIRCUIT

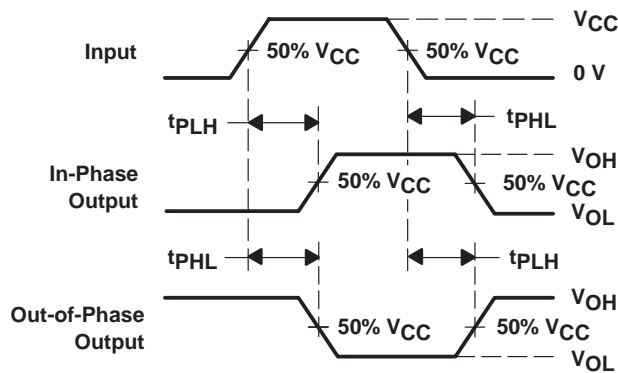
| TEST | S1 |
|-------------------|-------------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | $2 \times V_{CC}$ |
| t_{PHZ}/t_{PZH} | Open |



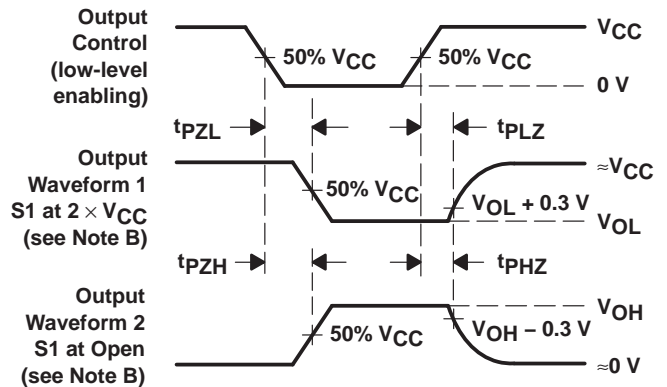
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.

Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.

D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| SN74AC563DBLE | OBSOLETE | SSOP | DB | 20 | | TBD | Call TI | Call TI |
| SN74AC563DBR | ACTIVE | SSOP | DB | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AC563DBRE4 | ACTIVE | SSOP | DB | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AC563DBRG4 | ACTIVE | SSOP | DB | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AC563DW | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AC563DWE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AC563DWG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AC563N | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74AC563NE4 | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74AC563PW | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AC563PWE4 | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AC563PWG4 | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AC563PWLE | OBSOLETE | TSSOP | PW | 20 | | TBD | Call TI | Call TI |
| SN74AC563PWR | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AC563PWRE4 | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AC563PWRG4 | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74AC563DBR | SSOP | DB | 20 | 2000 | 330.0 | 16.4 | 8.2 | 7.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74AC563PWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74AC563DBR | SSOP | DB | 20 | 2000 | 346.0 | 346.0 | 33.0 |
| SN74AC563PWR | TSSOP | PW | 20 | 2000 | 346.0 | 346.0 | 33.0 |

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|---------------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| SN74AC563DBR | ACTIVE | SSOP | DB | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AC563 | Samples |
| SN74AC563DW | ACTIVE | SOIC | DW | 20 | 25 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AC563 | Samples |
| SN74AC563N | ACTIVE | PDIP | N | 20 | 20 | RoHS & Non-Green | NIPDAU | N / A for Pkg Type | -40 to 85 | SN74AC563N | Samples |
| SN74AC563PW | ACTIVE | TSSOP | PW | 20 | 70 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AC563 | Samples |
| SN74AC563PWR | ACTIVE | TSSOP | PW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AC563 | Samples |

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LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74AC563DBR | SSOP | DB | 20 | 2000 | 330.0 | 16.4 | 8.2 | 7.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74AC563PWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74AC563DBR | SSOP | DB | 20 | 2000 | 356.0 | 356.0 | 35.0 |
| SN74AC563PWR | TSSOP | PW | 20 | 2000 | 356.0 | 356.0 | 35.0 |

TUBE


*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|-------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| SN74AC563DW | DW | SOIC | 20 | 25 | 507 | 12.83 | 5080 | 6.6 |
| SN74AC563N | N | PDIP | 20 | 20 | 506 | 13.97 | 11230 | 4.32 |
| SN74AC563PW | PW | TSSOP | 20 | 70 | 530 | 10.2 | 3600 | 3.5 |



4220206/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB0020A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4214851/B 08/2019

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

NOTES:

- All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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